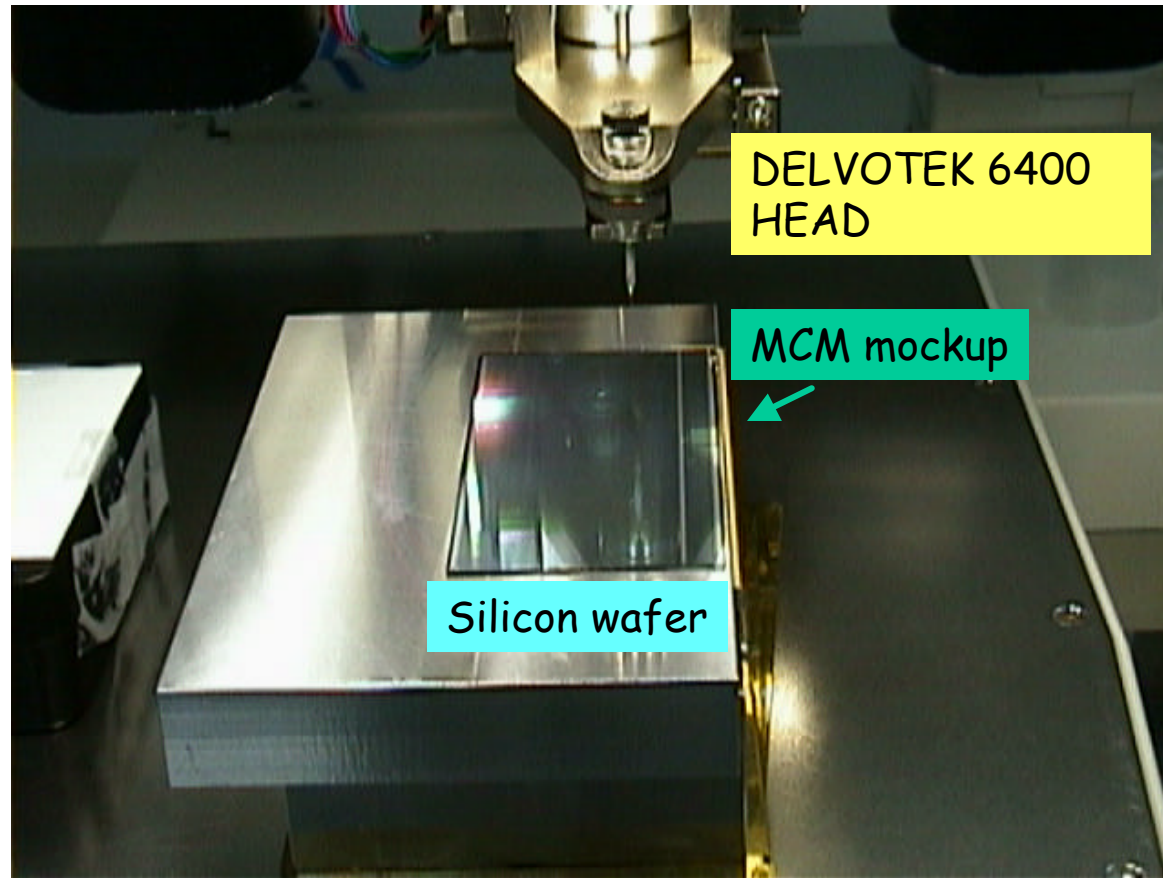


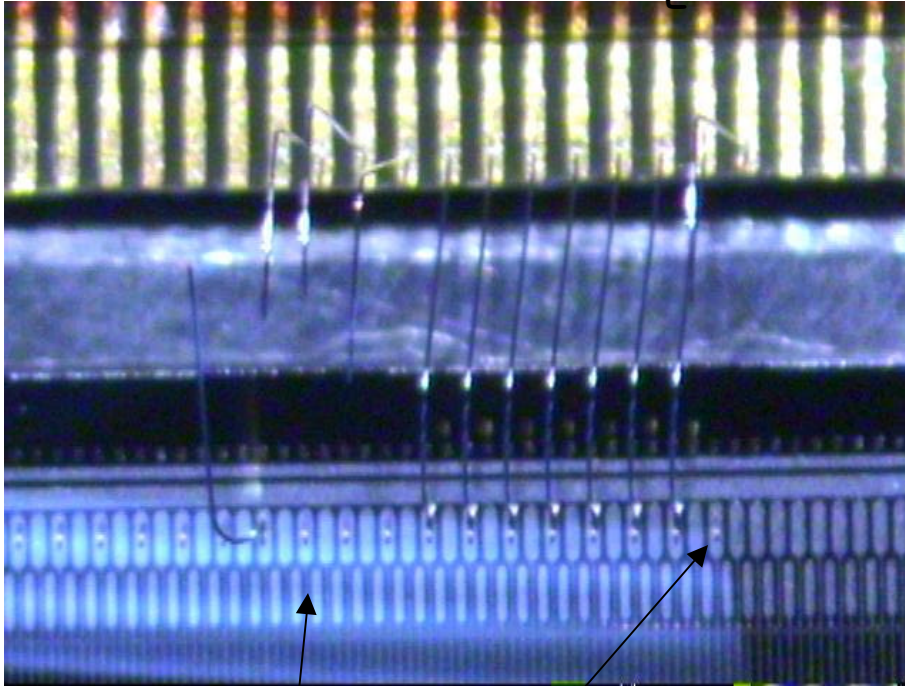
# BONDING TEST BETWEEN A SILICON WAFER AND THE MCM PITCH ADAPTER.

G&A ENGINEERING TCHR\_2K22011\_1A06/Rev A



EXPERIMENTAL SETUP

R  
E



Tested bonds

## RESULTS

West Bond 70PTE-75  
Destructive pull test

Bonding number	Breaking force	Broken side
1	8.4 g	Upilex side
2	9.2 g	Silicon side
3	8.7 g	Silicon side
4	9.2 g	Silicon side
10	9.1 g	Silicon side